TOSHIBA Power MOS FET Module Silicon N Channel MOS Type (L²-π-MOSV 4 in 1)

MP4209

High Power, High Speed Switching Applications
For Printer Head Pin Driver and Pulse Motor Driver
For Solenoid Driver

- 4 V gate drive available
- Small package by full molding (SIP 10 pin)
- High drain power dissipation (4 devices operation) : $P_T = 4 \text{ W (Ta} = 25^{\circ}\text{C)}$
- Low drain-source ON resistance: RDS (ON) = 0.28Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 3.5 \text{ S (typ.)}$
- Low leakage current: $I_{GSS} = \pm 10 \mu A \text{ (max) (V}_{GS} = \pm 16 \text{ V)}$

 $I_{DSS} = 100 \, \mu A \, (max) \, (V_{DS} = 100 \, V)$

• Enhancement-mode: $V_{th} = 0.8 \text{ to } 2.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	100	V	
Drain-gate voltage (R_{GS} = 20 k Ω)		V _{DGR}	100	V	
Gate-source voltage	Gate-source voltage		±20	V	
	DC	I _D	3	۸	
Drain current	Pulse	I _{DP}	12	Α	
Drain power dissipation (1 device operation, Ta = 25°C)		P _D	2.0	W	
Drain power dissipation (4 devices operation, Ta = 25°C)		P _{DT}	4.0	W	
Single pulse avalanche energy (Note 1)		E _{AS}	140	mJ	
Avalanche current		I _{AR}	3	Α	
Repetitive avalanche energy (Note 2)	1 device operation	E _{AR}	0.2	mJ	
	4 devices operation	E _{ART}	0.4		
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	−55 to 150	°C	

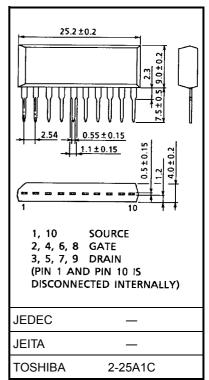
Note 1: Avalanche energy (single pulse) applied condition V_{DD} = 50 V, starting T_{ch} = 25°C, L = 20 mH, R_G = 25 Ω , I_{AR} = 3 A

Note 2: Repetitive rating; pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device. Please handle with caution.

Industrial Applications

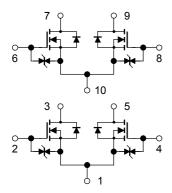
Unit: mm



Weight: 2.1 g (typ.)



Array Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit	
Thermal resistance of channel to ambient	ΣR _{th (ch-a)}	31.2	°C/W	
(4 devices operation, Ta = 25°C)	. (/			
Maximum lead temperature for soldering purposes	TL	260	°C	
(3.2 mm from case for t = 10 s)	_			

Electrical Characteristics (Ta = 25°C)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage curi	rent	I _{GSS}	V _{GS} = ±16 V, V _{DS} = 0 V	_	_	±10	μΑ
Drain cut-off curre	ent	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	100	_	_	V
Gate threshold vo	ltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	0.8	_	2.0	V
Drain-source ON resistance		R _{DS (ON)}	V _{GS} = 4 V, I _D = 2 A	_	0.36	0.45	Ω
			V _{GS} = 10 V, I _D = 2 A	1	0.28	0.35	
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 2 A	1.5	3.5	-	S
Input capacitance		C _{iss}	V = 10 V V = 0 V	_	280	_	pF
Reverse transfer capacitance Output capacitance		C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}$ - f = 1 MHz	_	50	_	pF
		Coss		-	105	_	pF
Switching time Fall time Turn-off time	Rise time	t _r	V_{GS} $V_{DD} \approx 50 \text{ V}$ V_{IN} : t_r , $t_f < 5 \text{ ns, duty} \le 1\%$, $t_w = 10 \text{ µs}$	_	20	_	- ns
	Turn-on time	t _{on}		1	50	ı	
	Fall time	t _f		ı	40		
	Turn-off time	t _{off}		-	170	_	
Total gate charge (gate-source plus		Qg	V _{DD} ≈ 80 V, V _{GS} = 10 V	-	13.5	_	nC
Gate-source charge		Q _{gs}	I _D = 3 A	_	8.5	_	nC
Gate-drain ("miller") charge		Q _{gd}		_	5	_	nC

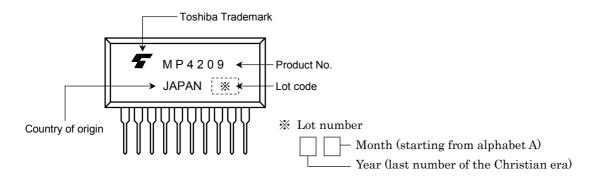
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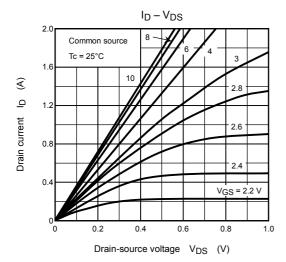


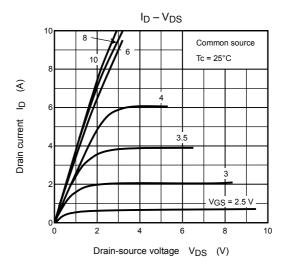
Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

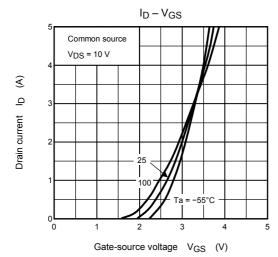
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current	I_{DR}	_	_	_	3	Α
Pulse drain reverse current	I _{DRP}	_	-	-	12	Α
Diode forward voltage	V _{DSF}	I _{DR} = 3 A, V _{GS} = 0 V	_	_	-1.5	V
Reverse recovery time	t _{rr}	I _{DR} = 3 A, V _{GS} = 0 V	_	100	_	ns
Reverse recovery charge	Q _{rr}	dl _{DR} /dt = 50 A/μs	_	0.2	_	μC

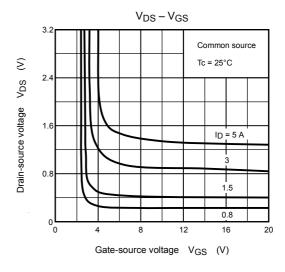
Marking

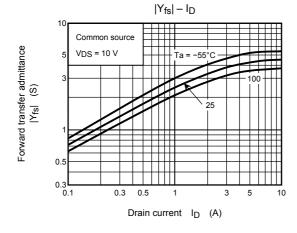


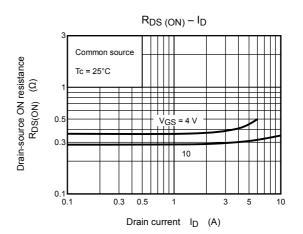


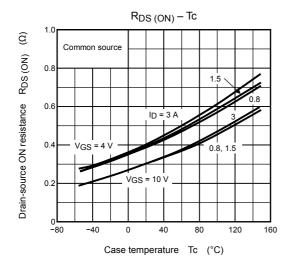


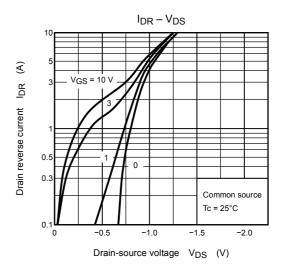


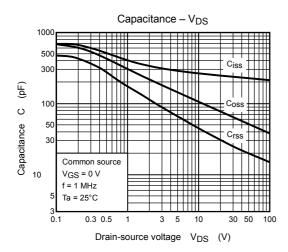


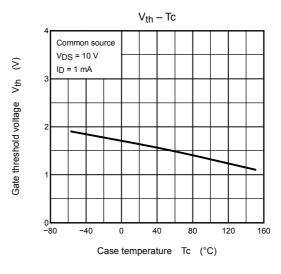


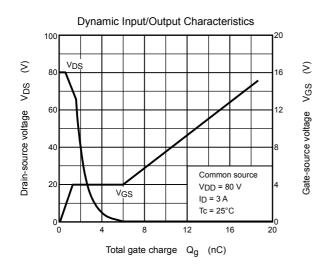


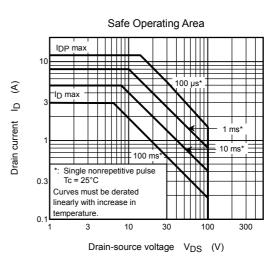


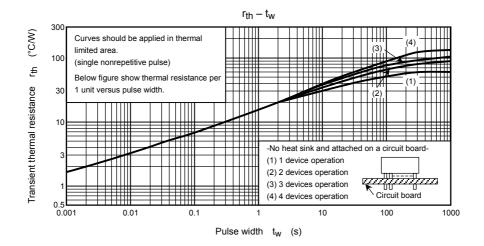


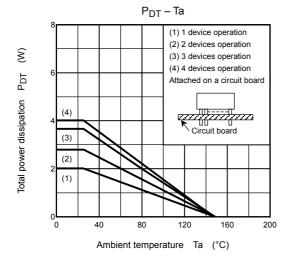


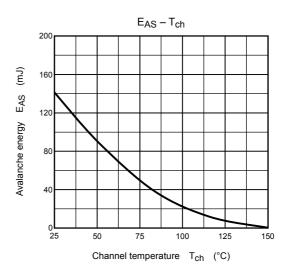


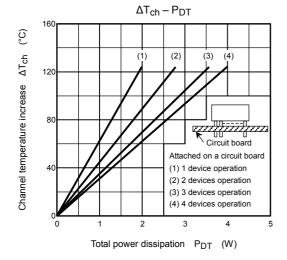


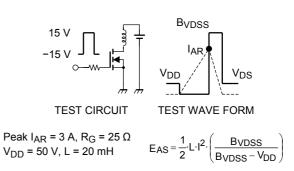












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